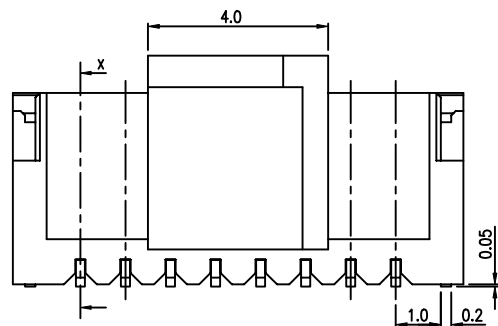
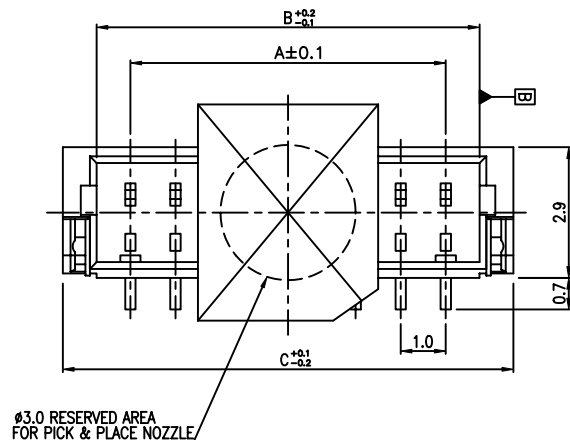
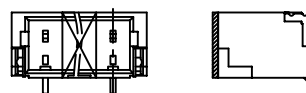
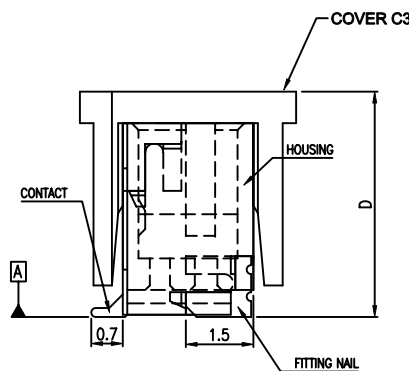
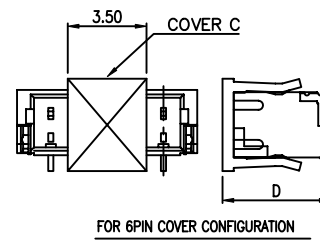
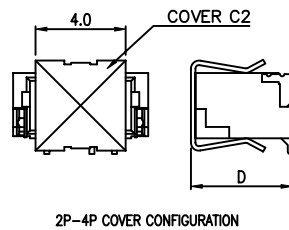
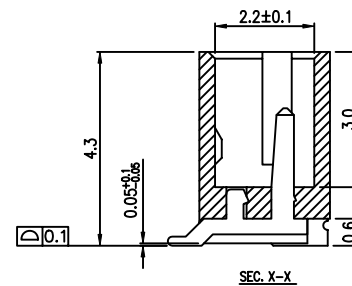


PCB PATTERN LAYOUT



WITH MYLAR CONFIGURATION



SEC. X-X

- NOTES:
1. MATERIAL:
 - 1.1 HOUSING: NYLON UL94V-0
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 - 1.4 COVER TYPES:
 - COVER-C2 :STAINLESS STEEL
 - COVER-C3 :NYLON UL94V-0
 - COVER-C : NYLON UL94V-0
 2. FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: MATTE TIN 100u" MIN. OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - MATTE TIN PLATING 100u" MIN. OVERALL
 3. REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
 4. SPEC. PLS. REFER TO GS-12-572.
 5. PACKAGE PLS. REFER TO GS-14-1314.
 6. PART NUMBER DESCRIPTION:

10089715-XXX 0 0 0 LF

 - NO OF CONTACTS
 - PACKING
 - 0: TAPE REEL
 - PLATING
 - 0: MATTE TIN
 - LEAD FREE
 - COLOR
 - 0: NATURAL

CKT	Dim.A	Dim.B	Dim.C	Dim.D
004	3.0	4.4	6.0	4.5
005	4.0	5.4	7.0	5.0
006	5.0	6.4	8.0	4.8
007	6.0	7.4	9.0	5.0
008	7.0	8.4	10.0	5.0
010	9.0	10.4	12.0	5.0
012	11.0	12.4	14.0	5.0

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI			
ltr	ecn no	dr	date	linear	.X ± 0.25	projection		www.fciconnect.com			
E	T09-1108	WL	08/19/09		.XX ± 0.15			title 1.0mm WIRE TO BOARD CONN. WAFER SMT S/T TYPE			
F	T09-1151	WL	11/25/09		.XXX ± 0.10						
G	T10-0004	WL	01/05/10	angles	0° ± 2°			product family WIRE TO BOARD size dwg no 10089715			
H	T10-0064	WL	05/17/10	dr	LEIF SHEN 06/18/08	MM					
				enr	LEIF SHEN 06/18/08			code TWN			
				chr	LEIF SHEN 06/18/08						
				appd	JOSEPH HSIA 06/18/08	scale		sheet 1 of 1			
sheet index	revision sheet	H	1								